

Special Issue on Microsensor and Microactuator Technologies and Their Practical Application



The last decades have seen a tremendous increase in the types of materials available to engineers, enabling the design and manufacturing of a vast set of products and services with a wide range of applications within industries such as ICT, health, energy, and transportation.

The convergence phenomenon between materials, physics, chemistry, biology, and electronics keeps accelerating, which paves the way for groundbreaking research leading to evermore innovative technologies and applications.

The purpose of this special issue is to disseminate recent works appealing to a wide audience on issues related to the exploitation of advances in materials science and engineering for the development of microsensor and microactuator technologies, as well as their practical applications.

Potential topics include but are not limited to the following:

- Advances in materials for the development of microsensor technologies, including microelectronics, nanoelectronics, bioelectronics, lab-on-a-chip, and microfluidics
- Advances in materials for the development of microactuator technologies that achieve both high-precision and ultralow energy consumption
- ▶ Demonstration of the practicability and effectiveness of the above developments, including *ex vivo* and *in vivo* biomedical, health monitoring, and Industry 4.0 applications

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